

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-11 (Canceled).

Claim 12 (Currently Amended): ~~The composition for a polishing pad according to claim 11~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and water-soluble particles dispersed in the water-insoluble matrix material, wherein said water-soluble particles are provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part, wherein said water-soluble particles are selected from the group consisting of (1) organic water-soluble particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, (2) inorganic water-soluble particles comprising at least one material selected from the group consisting of potassium acetate, potassium nitrate, potassium carbonate, potassium bicarbonate, potassium chloride, potassium bromide, potassium phosphate and magnesium nitrate, and (3) mixtures of (1) and (2).

Claim 13 (Original): The composition for a polishing pad according to claim 12, wherein the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

Claim 14 (Withdrawn): A polishing pad characterized in that at least a part of said polishing pad comprises the composition of a water-insoluble matrix material containing a

crosslinked polymer and water-soluble particles dispersed in the water-insoluble matrix material.

Claim 15 (Withdrawn): A polishing pad according to claim 14, wherein the elongation remaining after breaking is 100% or less when a test piece comprising the water-insoluble matrix material is broken at 80°C.

Claim 16 (Withdrawn): A polishing pad according to claim 15, wherein the Shore D hardness is 35 or more.

Claim 17 (Canceled).

Claim 18 (Currently Amended): ~~The composition for a polishing pad according to claim 17~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and organic water-soluble particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, dispersed in the water-insoluble matrix material, wherein the elongation remaining after breaking is 100% or less when a test piece comprising the water-insoluble matrix material is broken at 80°C.

Claim 19 (Currently Amended): ~~The composition for a polishing pad according to claim 17~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and organic water-soluble particles comprising at

least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, dispersed in the water-insoluble matrix material, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

Claim 20 (Currently Amended): ~~The composition for a polishing pad according to~~
~~claim 17~~ A composition for a polishing pad which comprises a water- insoluble matrix
material containing a crosslinked polymer and organic water-soluble particles comprising at
least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose,
hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl
pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin,
sulfonated polyisoprene and sulfonated polyisoprene copolymer, dispersed in the water-
insoluble matrix material, wherein said crosslinked polymer is (1) a crosslinked polymer of
rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene
rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-
propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a
crosslinked polymer of resin selected from the group consisting of polyethylene and
polyvinylidene fluoride, or (3) an ionomer.

Claim 21 (Currently Amended): ~~The composition for a polishing pad according to~~
~~claim 17~~ A composition for a polishing pad which comprises a water- insoluble matrix
material containing a crosslinked polymer and organic water-soluble particles comprising at

least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, dispersed in the water-insoluble matrix material, wherein the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

Claim 22 (Currently Amended): ~~The composition for a polishing pad according to claim 17~~ A composition for a polishing pad which comprises a water-insoluble matrix material containing a crosslinked polymer and organic water-soluble particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, dispersed in the water-insoluble matrix material, wherein said water-soluble particles are provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part.

Claim 23 (Previously Presented): The composition for a polishing pad according to claim 22, wherein said outer shell is comprised of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

Claim 24 (Canceled).

Claim 25 (Currently Amended): ~~The composition for a polishing pad according to claim 24~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a polymer crosslinked by an organic peroxide and organic water-soluble particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer dispersed in the water-insoluble matrix material, wherein said crosslinked polymer is (1) a crosslinked polymer of rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a crosslinked polymer of resin selected from the group consisting of polyethylene and polyvinylidene fluoride, or (3) an ionomer.

Claim 26 (Currently Amended): ~~The composition for a polishing pad according to claim 24~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a polymer crosslinked by an organic peroxide and organic water-soluble particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer dispersed in the water-insoluble matrix material, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

Claim 27 (Currently Amended): ~~The composition for a polishing pad according to claim 24~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a polymer crosslinked by an organic peroxide and organic water-soluble particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer dispersed in the water-insoluble matrix material, wherein the amount of said water-soluble particles is 10 to 90% by volume based on 100% by volume as the total amount of said water-insoluble matrix material and said water-soluble particles.

Claim 28 (Currently Amended): ~~The composition for a polishing pad according to claim 24~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a polymer crosslinked by an organic peroxide and organic water-soluble particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer dispersed in the water-insoluble matrix material, wherein said water-soluble particles are provided with an outer shell for inhibiting moisture absorption in an at least a part of the outermost part.

Claim 29 (Previously Presented): The composition for a polishing pad according to claim 28, wherein said outer shell is comprised of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

Claim 30 (Currently Amended): ~~The composition for a polishing pad according to claim 11~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and water-soluble particles dispersed in the water-insoluble matrix material, wherein said water-soluble particles are provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part, wherein said crosslinked polymer is (1) a crosslinked polymer of rubber selected from the group consisting of 1,2-polybutadiene, butadiene rubber, isoprene rubber, acrylic rubber, acrylonitrile-butadiene rubber, styrene-butadiene rubber, ethylene-propylene rubber, silicone rubber, fluorine rubber and styrene-isoprene rubber, (2) a crosslinked polymer of resin selected from the group consisting of polyethylene and polyvinylidene fluoride, or (3) an ionomer.

Claim 31 (Currently Amended): ~~The composition for a polishing pad according to claim 11~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and water-soluble particles dispersed in the water-insoluble matrix material, wherein said water-soluble particles are provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part, wherein said water-insoluble matrix material is modified with at least one group selected from the group consisting of an acid anhydride group, a carboxyl group, a hydroxyl group, an epoxy group and an amino group.

Claim 32 (Currently Amended): ~~The composition for a polishing pad according to claim 11~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and water-soluble particles dispersed in the water-insoluble matrix material, wherein said water-soluble particles are provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part, wherein said

outer shell is comprises of at least one material selected from the group consisting of polypeptide, epoxy resin, polyimide, polyamide and polysilicate.

Claim 33 (Currently Amended): ~~The composition for a polishing pad according to claim 11~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and water-soluble particles dispersed in the water-insoluble matrix material, wherein said water-soluble particles are provided with an outer shell for inhibiting moisture absorption in at least a part of the outermost part, wherein said water-soluble particles have a particle size of 0.1 to 500 μm .

Claim 34 (Currently Amended): ~~The composition for a polishing pad according to claim 17~~ A composition for a polishing pad which comprises a water- insoluble matrix material containing a crosslinked polymer and organic water-soluble particles comprising at least one material selected from the group consisting of dextrin, cyclodextrin, mannitol, lactose, hydroxypropylcellulose, methylcellulose, starch, protein, polyvinyl alcohol, polyvinyl pyrrolidone, polyacrylic acid, polyethylene oxide, water-soluble photosensitive resin, sulfonated polyisoprene and sulfonated polyisoprene copolymer, dispersed in the water-insoluble matrix material, wherein said water-soluble particles have a particle size of 0.1 to 500 μm .

DISCUSSION OF THE AMENDMENT

Claims 12, 18-22, 25-28, and 30-34 have each been amended into independent form.

Claims 11, 17, and 24 have been canceled.

No new matter has been added by the above amendment. With entry thereof, Claims 12-13, 18-23, and 25-34 will be active; Claims 14-16 stand withdrawn from consideration.